

CLAIMS:

1. A heat conductive silicone composition comprising
  - (a) 100 parts by weight of an organopolysiloxane
  - 5 having alkenyl groups only at both ends of a molecular chain,
  - (b) 200 to 3,000 parts by weight of a heat conductive filler,
  - (c) an organohydrogenpolysiloxane having hydrogen atoms directly bonded to silicon atoms (Si-H groups) only at
  - 10 both ends of a molecular chain, in such an amount that 0.1 to 5 moles of Si-H groups are available per mole of alkenyl groups in component (a), and
  - (d) a platinum group base curing catalyst in an amount to give 0.1 to 500 ppm of platinum group element based on the
  - 15 weight of component (a).
2. The composition of claim 1 wherein the heat conductive filler is selected from the group consisting of metals, oxides, nitrides, silicides, artificial diamond and mixtures
- 20 thereof.
3. A heat conductive silicone article obtained by shaping the composition of claim 1 into a sheet.
- 25 4. A heat conductive silicone article shaped by applying the composition of claim 1 onto a heat dissipating sheet.